

## 60V N-Channel Enhancement Mode Power MOSFET

## Description

WMB85N06T2 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

## Features

- $V_{DS} = 60V$ ,  $I_D = 85A$   
 $R_{DS(on)} < 3.6m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(on)} < 5.4m\Omega$  @  $V_{GS} = 4.5V$
- Low  $R_{DS(on)}$
- Low Gate Charge
- 100% EAS Guaranteed

## Applications

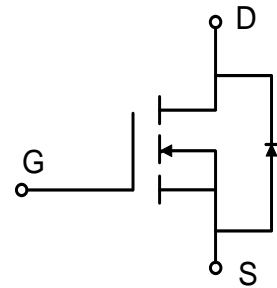
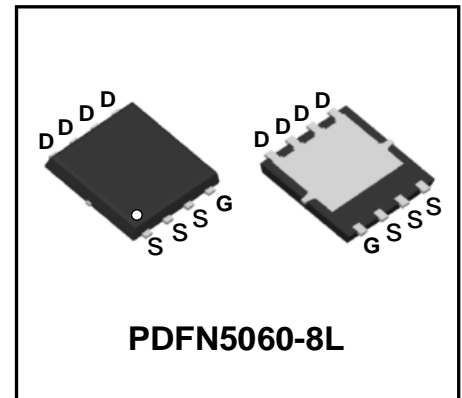
- Power Management Switches
- Synchronous Rectification for AC/DC Quick Charger

## Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source voltage		$V_{DS}$	60	V
Gate-Source voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$T_C = 25^\circ C$	$I_D$	85	A
	$T_C = 100^\circ C$		66	
Pulsed Drain Current <sup>2</sup>		$I_{DM}$	241	A
Single Pulse Avalanche Energy <sup>3</sup>		<b>EAS</b>	51.2	mJ
Avalanche Current		$I_{AS}$	32	A
Total Power Dissipation <sup>4</sup>	$T_C = 25^\circ C$	$P_D$	81	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	56	$^\circ C/W$
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	1.54	$^\circ C/W$



**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60	-	-	V
Gate-body Leakage current		I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T <sub>J</sub> =25°C	I <sub>DSS</sub>	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V	-	-	1	μA
	T <sub>J</sub> =55°C			-	-	5	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.2	1.7	2.3	V
Drain-Source On-Resistance <sup>2</sup>		R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	2.5	3.6	mΩ
			V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 15A	-	3.8	5.4	
Forward Trans conductance <sup>2</sup>		g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 20A	-	66	-	S
Dynamic Characteristics							
Input Capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> =0V, f =1MHz	-	3550	-	pF
Output Capacitance		C <sub>oss</sub>		-	1226	-	
Reverse Transfer Capacitance		C <sub>rss</sub>		-	78	-	
Switching Characteristics							
Gate Resistance		R <sub>g</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> =0V, f =1MHz	-	0.7	-	Ω
Total Gate Charge		Q <sub>g</sub>	V <sub>GS</sub> = 10V,V <sub>DS</sub> = 30V, I <sub>D</sub> = 20A	-	60	-	nC
Gate-Source Charge		Q <sub>gs</sub>		-	18	-	
Gate-Drain Charge		Q <sub>gd</sub>		-	4.6	-	
Turn-On Delay Time		t <sub>d(on)</sub>	V <sub>GS</sub> =10V, V <sub>DD</sub> = 30V R <sub>G</sub> = 3Ω, I <sub>D</sub> = 20A	-	18.5	-	nS
Rise Time		t <sub>r</sub>		-	7.9	-	
Turn-Off Delay Time		t <sub>d(off)</sub>		-	51	-	
Fall Time		t <sub>f</sub>		-	10.2	-	
Drain-source body diode Characteristics							
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>		I <sub>S</sub>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	-	-	85	A
Body Diode Reverse Recovery Time		t <sub>rr</sub>	I <sub>F</sub> = 20A, dI/dt = 100A/μs	-	25	-	nS
Body Diode Reverse Recovery Charge		Q <sub>rr</sub>		-	86	-	nC

## Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is  $V_{DD} = 50V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 32A$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

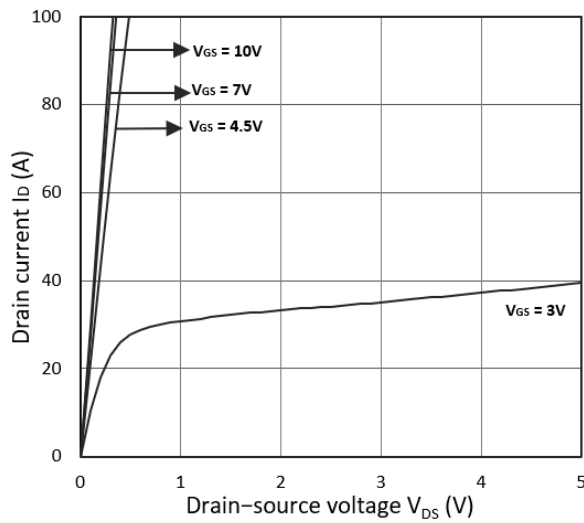


Figure 1. Output Characteristics

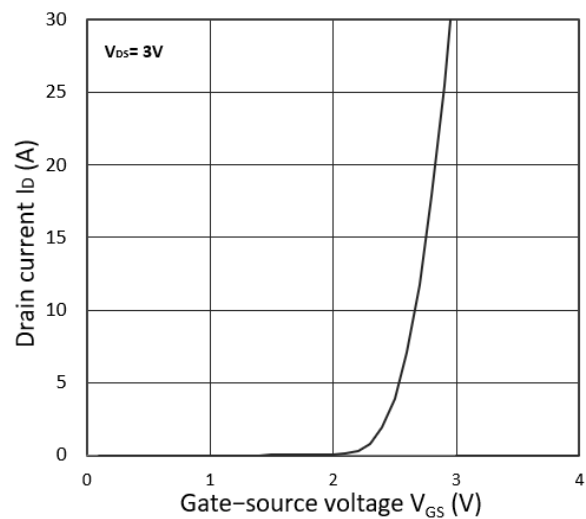


Figure 2. Transfer Characteristics

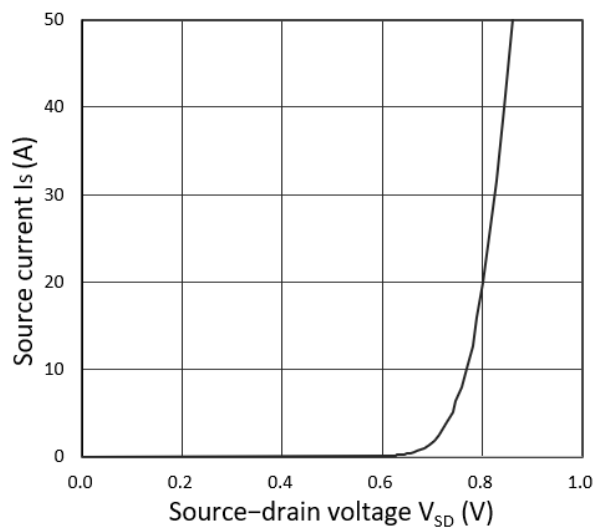


Figure 3. Forward Characteristics of Reverse

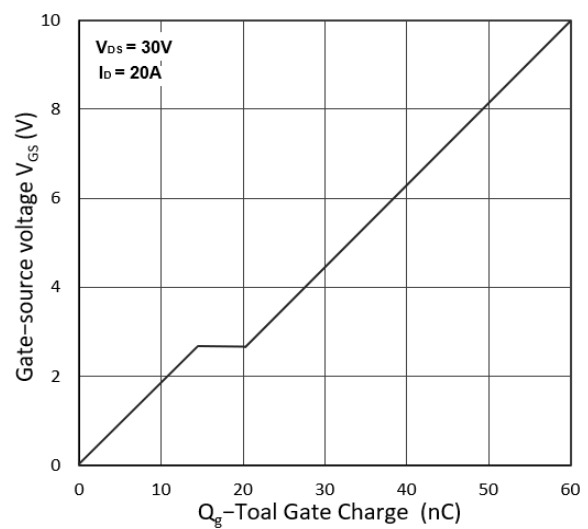
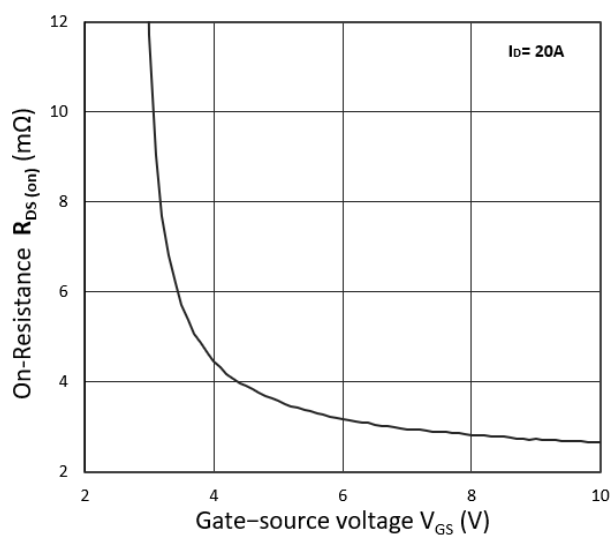
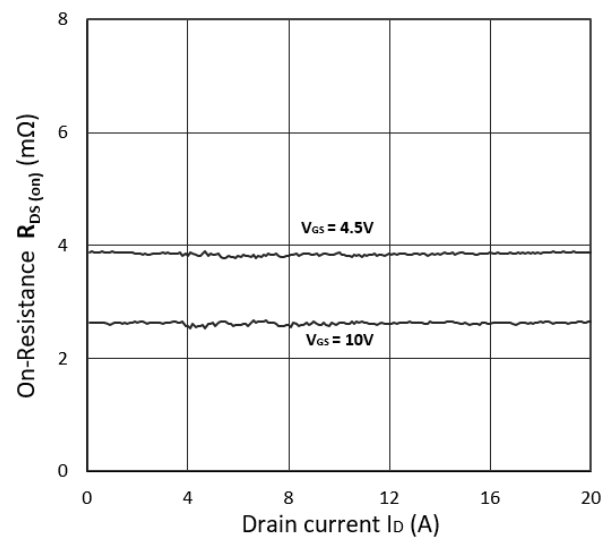


Figure 4. Gate Charge Characteristics

Figure 5.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 6.  $R_{DS(on)}$  vs.  $I_D$

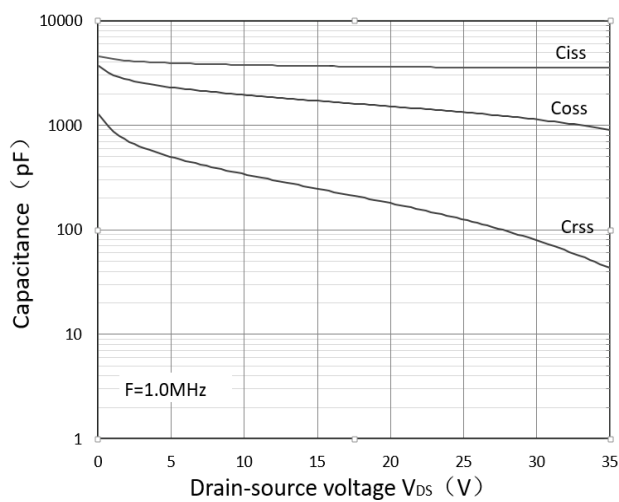


Figure 7. Capacitance Characteristics

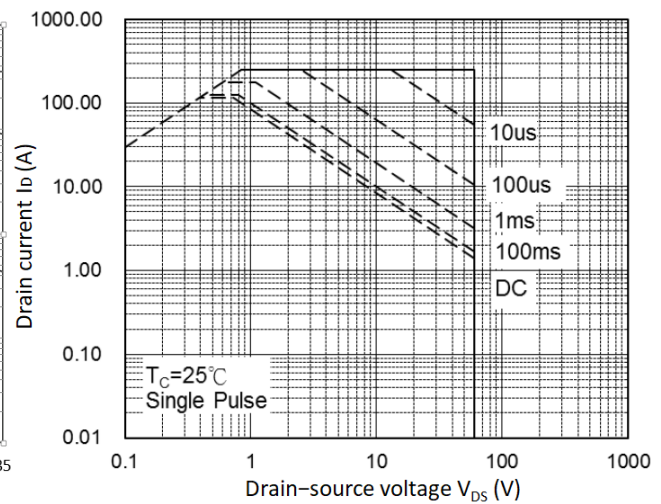


Figure 8. Safe Operating Area

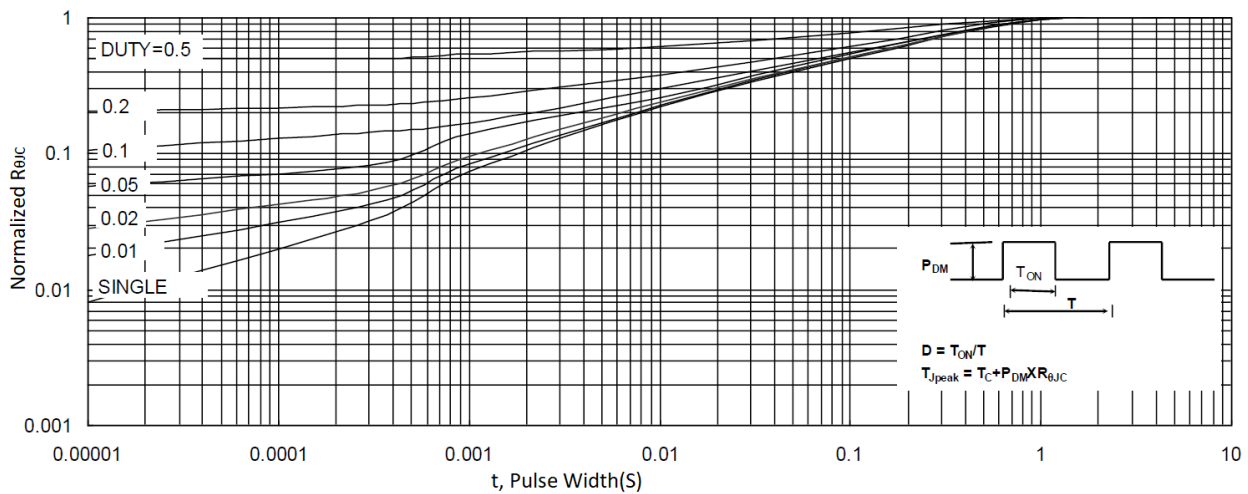


Figure 9. Normalized Maximum Transient Thermal Impedance

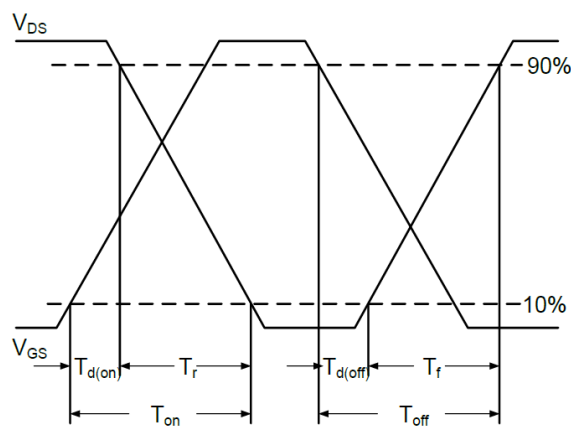
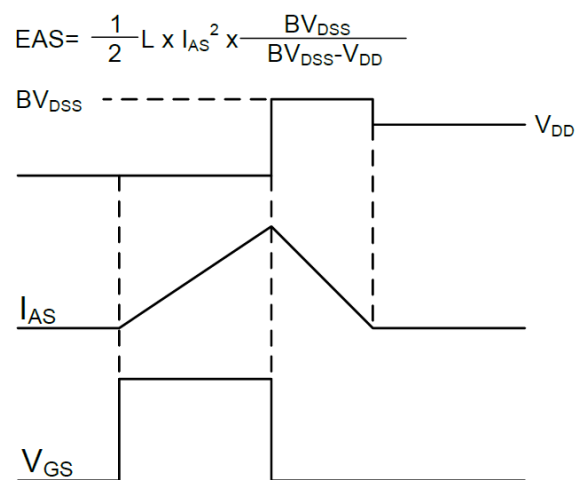


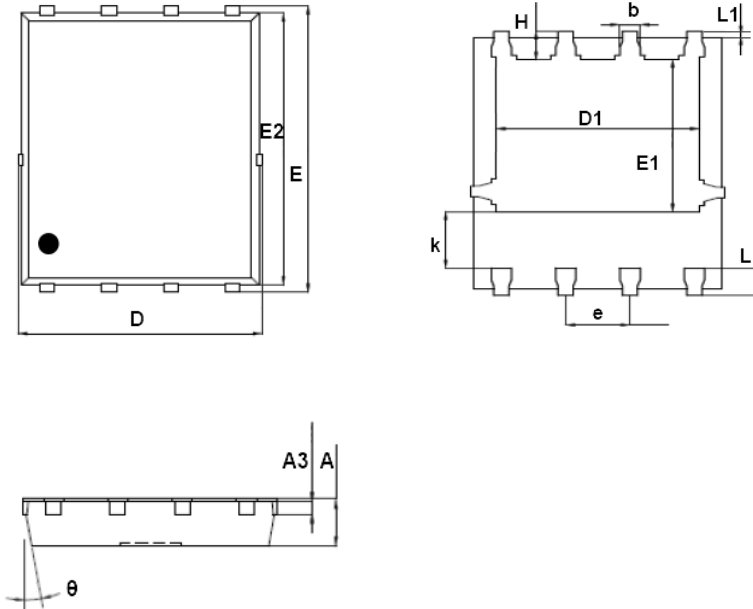
Figure 10. Switching Time Waveform

Figure 11. Unclamped Inductive Switching  
Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

## Mechanical Dimensions for PDFN5060-8L

## COMMON DIMENSIONS

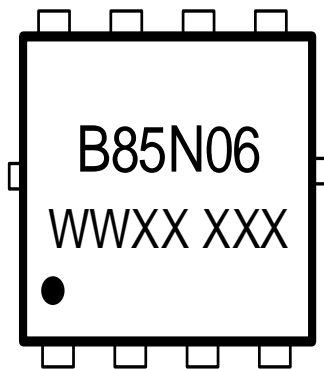


SYMBOL	MM	
	MIN	MAX
A	0.90	1.20
A3	0.15	0.35
D	4.80	5.40
E	5.90	6.35
D1	3.61	4.31
E1	3.3	3.92
E2	5.65	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.61
$\theta$	0°	12°

## Ordering Information

Part	Package	Marking	Packing method
WMB85N06T2	PDFN5060-8L	B85N06	Tape and Reel

## Marking Information



B85N06 = Device code

WWXX XXX= Date code

## Contact Information

No.1001, Shiwan(7) Road, Pudong District, Shanghai, P.R.China.201207

Tel: 86-21-50310888 Fax: 86-21-50757680 Email: market@way-on.com

WAYON website: <http://www.way-on.com>

For additional information, please contact your local Sales Representative.

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